

The present application is believed to be in condition for a full and thorough examination on the merits. An early and favorable consideration of the present application is hereby respectfully requested.

Respectfully submitted,

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IN THE CLAIMS

--22. (Amended) A guide according to [one of the claims] claim 15 [to 21], wherein the mold is made out of a material chosen from among stainless steel 316L with chemical deburring, or graphite, or Teflon, or silicon.

Claims 23-28 (New).--

IN THE ABSTRACT

--ABSTRACT OF THE DISCLOSURE

[METHOD FOR THE MAKING OF SOLDER CONNECTION PADS ON A SUBSTRATE AND GUIDE FOR THE IMPLEMENTATION OF THE METHOD]

A method for molding and soldering electrical connection pads to the electrical connection-receiving zones of electronic components or circuits [comprises] includes an operation for the injection of conductive liquid alloy into a guide open at one end placed so as to face the connection-receiving zone of the component. The guide is formed by two separable parts, a mold and an injection matrix, the mold and the injection matrix [comprising] including passages, with a narrowing of the guide at the level of the separation of the parts, and the parts of the guide are separated while the alloy is in the liquid state.

[Applications:] Such a method may find particular application to, as an example, making [of]  
connection pads for substrates or electronic components.

[Figure 8]--

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